

In The Claims

1. (Cancelled)

2. - 39. (Cancelled)

40. (Currently amended) A material composition comprising Si, C, O and H, said composition having a non-polymeric, covalently bonded structure comprising Si-C, Si-H, Si-O and C-H bonds and a dielectric constant of not more than 3.6, said composition further comprises between about 5 and about 40 atomic percent of Si; between about 5 and about 45 atomic percent of C; between 0 and about 50 atomic percent of O; and between about 10 and about 55 atomic percent of H, said composition further comprises at least one element selected from the group consisting of F, N, and Ge.

41. (Cancelled)

U.S.S.N. 10/827,065

42. (New) A material composition comprising Si, C, O and H, said composition having a non-polymeric, covalently bonded ring network structure comprising Si-C, Si-H, Si-O and C-H bonds and a dielectric constant of not more than 3.6, said composition further comprises between about 5 and about 40 atomic percent of Si; between about 5 and about 45 atomic percent of C; between 0 and about 50 atomic percent of O; and between about 10 and about 55 atomic percent of H, said composition further comprises at least one element selected from the group consisting of F, N, and Ge.